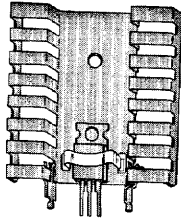


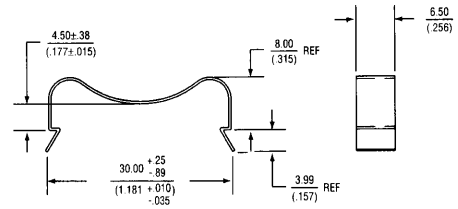
SECONDARY CLIPS



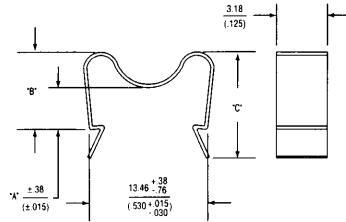
- Replace torqued hardware in assembling transistors to heat sinks.
- Snap into heat sink slots to hold the device in place for PC board insertion.

CLP-211 U.S. Patent No. 5,068,764

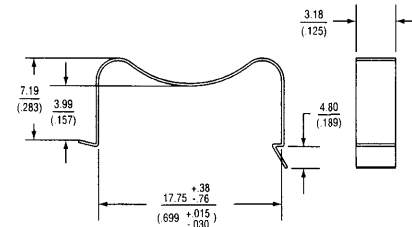
CATALOG NO.	DIM "A" mm (inches)	DIM "B" mm (inches)	DIM "C" mm (inches)
CLP-201	4.19 (.165)	8.89 (.350)	13.59 (.535)
CLP-202	5.72 (.225)	10.41 (.410)	15.11 (.595)
CLP-206	26.01 (1.024)	14.00 (.551)	7.49 (.295)
CLP-207	16.00 (.630)	11.00 (.433)	3.50 (.138)



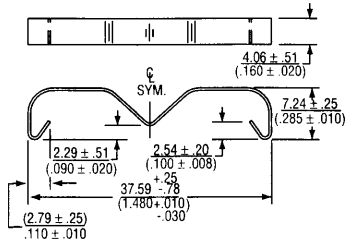
▲ CLP-101



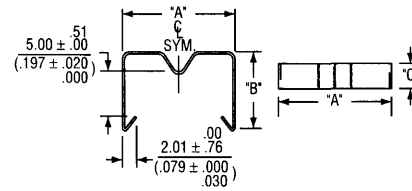
▲ CLP-201, CLP-202



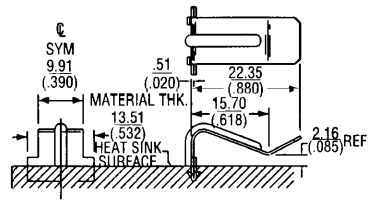
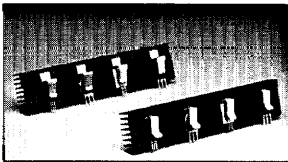
▲ CLP-203



▲ CLP-204



▲ CLP-206, CLP-207



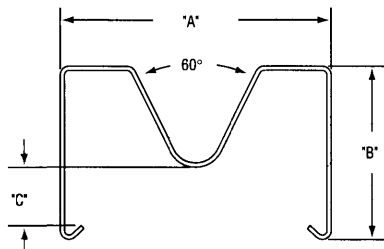
▲ CLP-211

Mounting slot requirements in heat sinks used with CLP-211:
Extrusions: 1.32mm ± .15mm (.052" ± .006) wide x 3.30mm (.130") minimum deep slot.

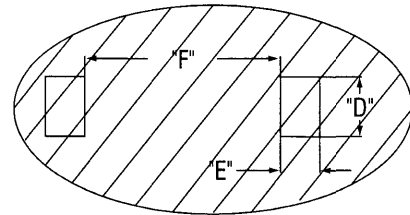
Stampings: Due to variations in stampings, please contact the factory for slot requirements. The CLP-211 will protrude from the back surface as much as 1.90mm (.075"), depending on material thickness.

CLP-211: U.S. Patent No. 5,068,764

U.K. Patent No. 2,243,026



▲ 7701, 8601



▲ RECOMMENDED PUNCH FORMAT

PART NO.	CASE STYLE	DIM "A" mm (inches)	DIM "B" mm (inches)	DIM "C" mm (inches)	DIM "D" mm (inches)	DIM "E" mm (inches)	DIM "F" mm (inches)	MATERIAL WIDTH	MATERIAL THICKNESS
7701	T0220	16.0 (.630)	11.0 (.433)	4.75 (.187)	4.5 (.177)	3.0 (.118)	15.0 (.59)	3.5-4.0 (.138-.157)	0.3 (.012)
8601	T0247	26.0 (1.024)	14.0 (.551)	4.75 (.187)	8.0 (.315)	2.5 (.098)	25.0 (.984)	7.5 (.295)	0.4 (.098)